

REMARKS

Claims 2-4, 7-16, 28-29, and 31-35 are pending. Claims 7, 11, 28, 32 and 34 have been amended. No new matter has been introduced by these amendments.

Claims 28 stands rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Pat. No. 5,098,630 to Ogui. Applicants respectfully request reconsideration of this rejection.

Claim 28 recites an imaging device that includes, *inter alia*, “a rigid housing having a cavity defined by side walls and a closed bottom.” A semiconductor imaging chip is “located within said cavity of said housing.” The semiconductor imaging chip is “encapsulated in a transparent material...disposed within said cavity.” The transparent material is “*fully contained* by said side walls and closed bottom of said housing.”

Ogui does not disclose transparent material “*fully contained* by said side walls and closed bottom of said housing.” In Fig. 5 of Ogui (and in every other disclosed embodiment), the transparent material 21 extends out and over the sidewalls of the rigid housing 2. Applicants respectfully submit that claim 28 and all dependent claims are patentable over Ogui.

Claims 2-4, 7-10 and 32 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 6,291,811 to Ogawa in view of U.S. Pat. No. 4,727,407 to Nobue. Applicants respectfully request reconsideration of this rejection.

Claim 7 recites an imaging device that includes, *inter alia*, “a package comprising a transparent material *fully contained* by [] side walls and [a] closed bottom and encapsulating said frame, support structure, and semiconductor imaging chip, said transparent material covering said chip,” and “photosensitive elements receiving said image through said transparent material.” Portions of the transparent material “through which light passes to said photosensitive elements have respective color tints to provide colored light filtering.”

Owaga discloses an imaging device in which a chip 90 encapsulated by transparent resin 95a. The transparent resin 95a is covered with a photo-shield layer 95b. Photo-shield layer 95b is black insulating paint. See Ogawa FIG. 16 and col. 12, line 59 to col. 13, line 16. Owaga does not disclose and does not anticipate an imaging device with “a rigid housing.”

Consequently, Owaga does not disclose and does not anticipate a rigid housing having “a cavity defined by side walls and a closed bottom.”

Neither Owaga nor Nobue disclose “an imaging device” with a “a package comprising a transparent material *fully* contained by said side walls and closed bottom and encapsulating said frame, support structure, and semiconductor imaging chip,” and the transparent material “is tinted to provide colored light filtering.” Applicant respectfully request that the rejection of claim 7 and all dependent claims be withdrawn and the claims allowed.

Claim 34 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Ogawa in view of Nobue and further in view of U.S. Patent No. 5,378,916 to Mantell. Applicants respectfully request reconsideration of this rejection.

Claims 11-16 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Ogawa in view of U.S. Pat. No. 4,663,656 to Elabd et al. and further in view of Nobue. Applicants respectfully request reconsideration of this rejection.

Claim 11 recites an imaging system that includes, *inter alia*, “a transmitting system for transmitting an image including an image source, said transmitting system being arranged to transmit the entire image simultaneously onto each of a plurality of imaging devices.” Each imaging device includes a “frame, support structure, and respective semiconductor device...encapsulated in transparent material of a respective package for protecting and supporting each said semiconductor device, said transparent material being *fully* contained by said side walls and closed bottom and including injection molded resin.”

None of Ogawa, Elabd and Nobue disclose a transmitting system which includes a “frame, support structure, and respective semiconductor device...encapsulated in transparent material of a respective package for protecting and supporting each said semiconductor device, said transparent material being *fully* contained by said side walls and closed bottom and including injection molded resin.” Applicants respectfully request that the rejection of claim 11 and all dependent claims be withdrawn and the claims allowed.

Claim 29 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Ogiu in view of Ogawa. Applicants respectfully request reconsideration of this rejection.

Claim 29 depends from claim 28. The deficiencies of Ogiu have been discussed above. Ogawa does not cure these deficiencies. Specifically, Ogawa does not disclose transparent material “*fully* contained by said side walls and closed bottom of said housing.” Applicant respectfully requests that the rejection of claim 29 be withdrawn and the claim allowed.

Claim 31 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Ogiu in view of U.S. Patent No. 4,456,828 to Mason. Applicants respectfully request reconsideration of this rejection.

Claim 31 depends from claim 28. The deficiencies of Ogiu have been discussed above. Mason does not cure these deficiencies. Specifically, Ogawa does not disclose transparent material “*fully* contained by said side walls and closed bottom of said housing.” Applicant respectfully requests that the rejection of claim 31 be withdrawn and the claim allowed.

Claims 33 and 35 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Ogiu in view of U.S. Pat. No. 5,644,169 to Chun. Applicants respectfully request reconsideration of this rejection.

Claim 33 and 35 depend from claim 28. The deficiencies of Ogiu have been discussed above. Chun does not cure these deficiencies. Specifically, Chun does not disclose transparent material “*fully* contained by said side walls and closed bottom of said housing.” Applicant respectfully requests that the rejection of claim 31 be withdrawn and the claim allowed.

In view of the above amendment, applicant believes the pending application is in condition for allowance.

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